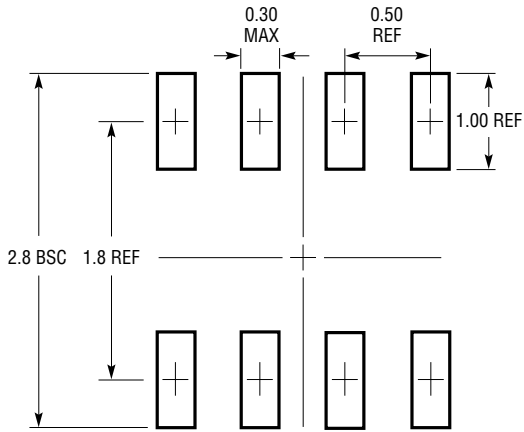
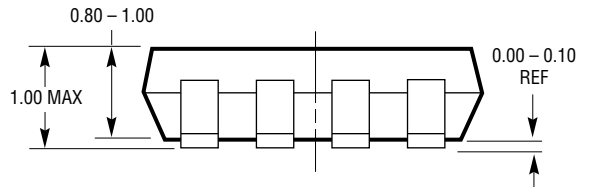
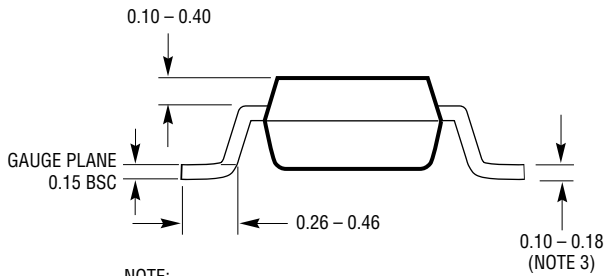
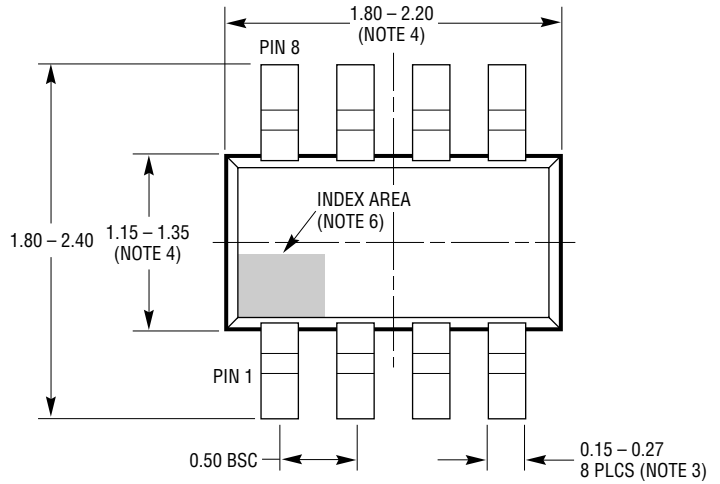


**SC8 Package**  
**8-Lead Plastic SC70**  
 (Reference LTC DWG # 05-08-1639 Rev 0)



RECOMMENDED SOLDER PAD LAYOUT  
 PER IPC CALCULATOR



SC8 SC70 0905 REV 0

- NOTE:
1. DIMENSIONS ARE IN MILLIMETERS
  2. DRAWING NOT TO SCALE
  3. DIMENSIONS ARE INCLUSIVE OF PLATING
  4. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH AND METAL BURR
  5. MOLD FLASH SHALL NOT EXCEED 0.254mm
  6. DETAILS OF THE PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE INDEX AREA
  7. EIAJ PACKAGE REFERENCE IS EIAJ SC-70 AND JEDEC MO-203 VARIATION BA